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RESPONSE UNDER 37 CFR 1.116 EXPEDITED PROCEDURE EXAMINING GROUP 2815

PATENT APPLICATION

Docket No.: 9898-341

Client Ref. No.: SS-18733-US-RCE

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Dong-Kil SHIN, et al.

Serial No.:

10/772,651

Examiner:

Warren, Matthew E.

Filed:

February 4, 2004

Group Art Unit:

2815

Confirmation No.:

5815

For:

MULTI-CHIP PACKAGE WITH SOFT ELEMENT AND METHOD OF

MANUFACTURING THE SAME

Date:

August 3, 2007

Mail Stop AF Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

## **AMENDMENT AFTER FINAL REJECTION UNDER 37 CFR 1.116**

Responsive to the Final Office Action, Paper No. 20061122, dated June 4, 2007, please amend the application as follows.

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 6 of this paper.